L Number	Hits	Search Text	DB	Time stamp
7	2	6437240.URPN.	USPAT	2004/11/03 12:49
8	3	5777385.URPN.	USPAT	2004/11/03 12:52
9	2	6162659.URPN.	USPAT	2004/11/03 12:53
10	446	((438/108.ccls. 438/122.ccls. 438/124.ccls. 438/127.ccls. 438/612.ccls. 438/613.ccls. 438/615.ccls.) and (solder adj (bump$5 ball protrusion)) and (heat near (sink spreader dissipat$6)) and ((flip ic circuit semiconductor) adj (chip die dice))) and ((substrate carrier module) with (pad contact electrode ubm underbump))	USPAT; US-PGPUB	2004/11/03 12:56
11	200	(solder adj (bump$5 ball protrusion)) same (heat near (sink spreader dissipat$6)) same ((flip ic circuit semiconductor) adj (chip die dice)) same ((substrate carrier module) with (pad contact electrode ubm underbump)) same (align$6 reflow$6 attach$6 underfill encapsulat$6 join$6 bond$6)	USPAT; US-PGPUB	2004/11/03 13:24
12	2	6507104.URPN.	USPAT	2004/11/03 13:43
13	69	(solder adj (bump$5 ball protrusion)) and (heat near (sink spreader dissipat$6)) and ((flip ic circuit semiconductor) adj (chip die dice)) and ((substrate carrier module) with (pad contact electrode ubm underbump)) and (align$6 reflow$6 attach$6 underfill encapsulat$6 join$6 bond$6)	EPO; JPO; DERWENT; IBM_TDB	2004/11/03 13:45
14	21	((bump$5 ball protrusion) near2 (heat near (sink spreader dissipat$6))) and ((flip ic circuit semiconductor) adj (chip die dice)) same ((substrate carrier module) with (pad contact electrode ubm underbump))	EPO; JPO; DERWENT; IBM_TDB	2004/11/03 13:55
15	25	((bump$5 ball protrusion) near2 (heat near (sink spreader dissipat$6))) same ((flip ic circuit semiconductor) adj (chip die dice)) same ((substrate carrier module) with (pad contact electrode ubm underbump))	USPAT; US-PGPUB	2004/11/03 13:56
16	54	(438/108.ccls. 438/122.ccls. 438/124.ccls. 438/127.ccls. 438/612.ccls. 438/613.ccls. 438/615.ccls.) and ((bump$5 ball protrusion) near2 (heat near (sink spreader dissipat$6)))	USPAT; US-PGPUB	2004/11/03 13:57